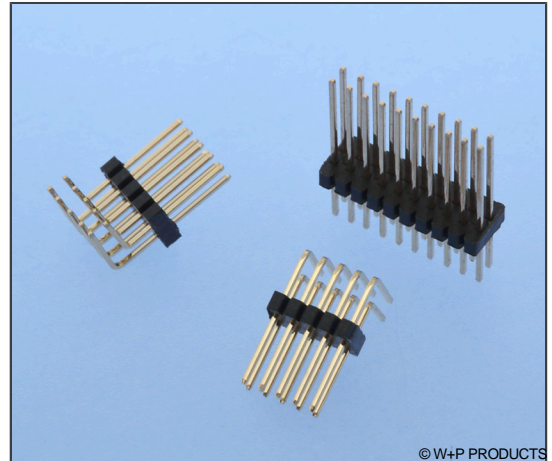


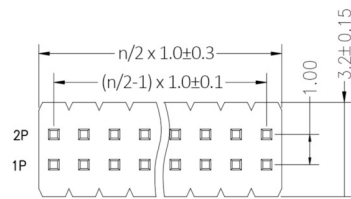
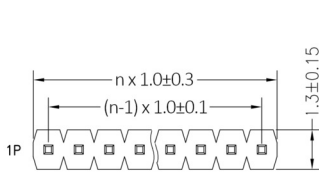
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
RoHS-Ausnahmen 6a-I / 6c <i>RoHS Exemptions 6a-I / 6c</i>	keine <i>none</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 30 mΩ <i>< 30 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 500 MΩ <i>> 500 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC <i>500 V AC</i>
Nennstrom <i>Current Rating</i>	0,75 A <i>0.75 A</i>
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C <i>-40 °C ... +105 °C</i>
Verarbeitung <i>Processing</i>	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden) <i>230 °C for 30-60 seconds (260 °C for 10 seconds)</i>

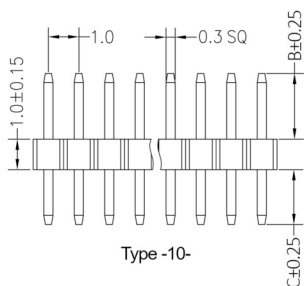
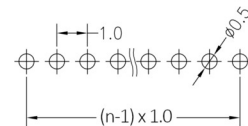


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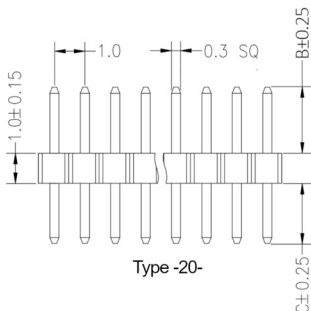
Passende Buchsenleisten:
Compatible Female Headers:
46-7091



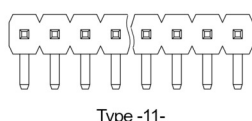
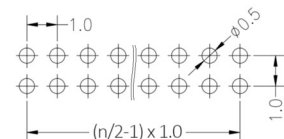
Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



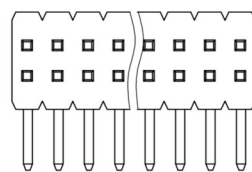
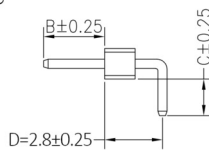
Type -10-



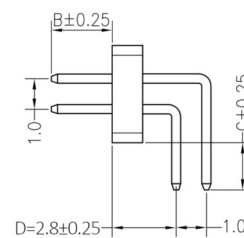
Type -20-



Type -11-



Type -21-



Series

46-721

Type*

11

10 Einreihig, gerade
Single row, straight
11 Einreihig, gewinkelt
Single row, right-angled
20 Zweireihig, gerade
Double row, straight
21 Zweireihig, gewinkelt
Double row, right-angled

Contacts*

016

001-028 Einreihig
Single row
002-040 Zweireihig
Double row

Dimensions*

10

10 B=3.20 C=6.50
20 B=2.10 C=2.10
30 B=3.20 C=2.10
40 B=4.00 C=2.10
99- Kundenspezifisch
Customer-specific

Plating

00

00 Vergoldet
Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

